

ABSTRACT OF THE DISCLOSURE

A function module and its manufacturing method. The function module includes a circuit board, a first device, a second device, a planarization member, and a plate-type heat dissipation device. The circuit board includes a surface. The first device is disposed on the surface. The second device is disposed on the surface, and the height of the second device is higher than the height of the first device. The planarization member, including a flat surface, is disposed on the surface in a manner such that the planarization member surrounds the first device and the second device. The height of the flat surface is not less than the height of the second device. The plate-type heat dissipation device is disposed on the flat surface.